L Number	Hits	Search Text	DB	Time stamp
1	1441	wafer$4 with flip$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/13 19:58
2	558	(wafer$4 with flip$4) and dic$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/13 19:59
3	77	((wafer$4 with flip$4) and dic$4) and (align$4 with wafer$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/13 20:00

L Number	Hits	Search Text	DB	Time stamp
1	1	"20020126941"	USPAT; US-PGPUB	2003/08/11 14:18
2	1	"20020126940"	USPAT; US-PGPUB	2003/08/11 14:21
3	614	wafer$2 with dic$4 with thickness	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/11 14:22
4	206	(wafer$2 with dic$4 with thickness) and dice	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/11 14:22
5	0	((wafer$2 with dic$4 with thickness) and dice) and optical	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/11 14:23
6	11	((wafer$2 with dic$4 with thickness) and dice) and lithographic$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/11 14:23